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### **Understanding Embedded - FPGAs (Field Programmable Gate Array)**

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

#### **Details**

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	3072
Total RAM Bits	36864
Number of I/O	84
Number of Gates	125000
Voltage - Supply	1.14V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 85°C (TA)
Package / Case	132-WFQFN
Supplier Device Package	132-QFN (8x8)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/microsemi/agl125v2-qng132i">https://www.e-xfl.com/product-detail/microsemi/agl125v2-qng132i</a>

**Table 2-10 • Quiescent Supply Current (IDD) Characteristics, IGLOO Sleep Mode\***

	Core Voltage	AGL015	AGL030	AGL060	AGL125	AGL250	AGL400	AGL600	AGL1000	Units
VCCI/VJTAG = 1.2 V (per bank) Typical (25°C)	1.2 V	1.7	1.7	1.7	1.7	1.7	1.7	1.7	1.7	µA
VCCI/VJTAG = 1.5 V (per bank) Typical (25°C)	1.2 V / 1.5 V	1.8	1.8	1.8	1.8	1.8	1.8	1.8	1.8	µA
VCCI/VJTAG = 1.8 V (per bank) Typical (25°C)	1.2 V / 1.5 V	1.9	1.9	1.9	1.9	1.9	1.9	1.9	1.9	µA
VCCI/VJTAG = 2.5 V (per bank) Typical (25°C)	1.2 V / 1.5 V	2.2	2.2	2.2	2.2	2.2	2.2	2.2	2.2	µA
VCCI/VJTAG = 3.3 V (per bank) Typical (25°C)	1.2 V / 1.5 V	2.5	2.5	2.5	2.5	2.5	2.5	2.5	2.5	µA

Note:  $IDD = N_{BANKS} \times ICCI$ . Values do not include I/O static contribution, which is shown in Table 2-10 through Table 2-15 on page 2-11 and Table 2-16 on page 2-11 through Table 2-18 on page 2-12 (PDC6 and PDC7).

**Table 2-11 • Quiescent Supply Current (IDD) Characteristics, IGLOO Shutdown Mode**

	Core Voltage	AGL015	AGL030	Units
Typical (25°C)	1.2 V / 1.5 V	0	0	µA

**Table 2-12 • Quiescent Supply Current (IDD), No IGLOO Flash\*Freeze Mode<sup>1</sup>**

	Core Voltage	AGL015	AGL030	AGL060	AGL125	AGL250	AGL400	AGL600	AGL1000	Units
<b>ICCA Current<sup>2</sup></b>										
Typical (25°C)	1.2 V	5	6	10	13	18	25	28	42	µA
	1.5 V	14	16	20	28	44	66	82	137	µA
<b>ICCI or IJTAG Current<sup>3</sup></b>										
VCCI/VJTAG = 1.2 V (per bank) Typical (25°C)	1.2 V	1.7	1.7	1.7	1.7	1.7	1.7	1.7	1.7	µA
VCCI/VJTAG = 1.5 V (per bank) Typical (25°C)	1.2 V / 1.5 V	1.8	1.8	1.8	1.8	1.8	1.8	1.8	1.8	µA
VCCI/VJTAG = 1.8 V (per bank) Typical (25°C)	1.2 V / 1.5 V	1.9	1.9	1.9	1.9	1.9	1.9	1.9	1.9	µA
VCCI/VJTAG = 2.5 V (per bank) Typical (25°C)	1.2 V / 1.5 V	2.2	2.2	2.2	2.2	2.2	2.2	2.2	2.2	µA
VCCI/VJTAG = 3.3 V (per bank) Typical (25°C)	1.2 V / 1.5 V	2.5	2.5	2.5	2.5	2.5	2.5	2.5	2.5	µA

Notes:

1.  $IDD = N_{BANKS} \times ICCI + ICCA$ . JTAG counts as one bank when powered.
2. Includes VCC, VPUMP, and VCCPLL currents.
3. Values do not include I/O static contribution (PDC6 and PDC7).

**Table 2-21 • Different Components Contributing to Dynamic Power Consumption in IGLOO Devices  
For IGLOO V2 Devices, 1.2 V DC Core Supply Voltage**

Parameter	Definition	Device Specific Dynamic Power ( $\mu$ W/MHz)							
		AGL1000	AGL600	AGL400	AGL250	AGL125	AGL060	AGL030	AGL015
PAC1	Clock contribution of a Global Rib	4.978	3.982	3.892	2.854	2.845	1.751	0.000	0.000
PAC2	Clock contribution of a Global Spine	2.773	2.248	1.765	1.740	1.122	1.261	2.229	2.229
PAC3	Clock contribution of a VersaTile row	0.883	0.924	0.881	0.949	0.939	0.962	0.942	0.942
PAC4	Clock contribution of a VersaTile used as a sequential module	0.096	0.095	0.096	0.095	0.095	0.096	0.094	0.094
PAC5	First contribution of a VersaTile used as a sequential module						0.045		
PAC6	Second contribution of a VersaTile used as a sequential module						0.186		
PAC7	Contribution of a VersaTile used as a combinatorial module	0.158	0.149	0.158	0.157	0.160	0.170	0.160	0.155
PAC8	Average contribution of a routing net	0.756	0.729	0.753	0.817	0.678	0.692	0.738	0.721
PAC9	Contribution of an I/O input pin (standard-dependent)	See Table 2-13 on page 2-10 through Table 2-15 on page 2-11.							
PAC10	Contribution of an I/O output pin (standard-dependent)	See Table 2-16 on page 2-11 through Table 2-18 on page 2-12.							
PAC11	Average contribution of a RAM block during a read operation	25.00							
PAC12	Average contribution of a RAM block during a write operation	30.00							
PAC13	Dynamic PLL contribution	2.10							

Note: For a different output load, drive strength, or slew rate, Microsemi recommends using the Microsemi power spreadsheet calculator or SmartPower tool in Libero SoC.

## Power Calculation Methodology

This section describes a simplified method to estimate power consumption of an application. For more accurate and detailed power estimations, use the SmartPower tool in Microsemi Libero SoC software.

The power calculation methodology described below uses the following variables:

- The number of PLLs as well as the number and the frequency of each output clock generated
- The number of combinatorial and sequential cells used in the design
- The internal clock frequencies
- The number and the standard of I/O pins used in the design
- The number of RAM blocks used in the design
- Toggle rates of I/O pins as well as VersaTiles—guidelines are provided in Table 2-23 on page 2-19.
- Enable rates of output buffers—guidelines are provided for typical applications in Table 2-24 on page 2-19.
- Read rate and write rate to the memory—guidelines are provided for typical applications in Table 2-24 on page 2-19. The calculation should be repeated for each clock domain defined in the design.

### **Methodology**

#### **Total Power Consumption— $P_{TOTAL}$**

$$P_{TOTAL} = P_{STAT} + P_{DYN}$$

$P_{STAT}$  is the total static power consumption.

$P_{DYN}$  is the total dynamic power consumption.

#### **Total Static Power Consumption— $P_{STAT}$**

$$P_{STAT} = (P_{DC1} \text{ or } P_{DC2} \text{ or } P_{DC3}) + N_{BANKS} * P_{DC5} + N_{INPUTS} * P_{DC6} + N_{OUTPUTS} * P_{DC7}$$

$N_{INPUTS}$  is the number of I/O input buffers used in the design.

$N_{OUTPUTS}$  is the number of I/O output buffers used in the design.

$N_{BANKS}$  is the number of I/O banks powered in the design.

#### **Total Dynamic Power Consumption— $P_{DYN}$**

$$P_{DYN} = P_{CLOCK} + P_{S-CELL} + P_{C-CELL} + P_{NET} + P_{INPUTS} + P_{OUTPUTS} + P_{MEMORY} + P_{PLL}$$

#### **Global Clock Contribution— $P_{CLOCK}$**

$$P_{CLOCK} = (P_{AC1} + N_{SPINE} * P_{AC2} + N_{ROW} * P_{AC3} + N_{S-CELL} * P_{AC4}) * F_{CLK}$$

$N_{SPINE}$  is the number of global spines used in the user design—guidelines are provided in the "Spine Architecture" section of the *IGLOO FPGA Fabric User Guide*.

$N_{ROW}$  is the number of VersaTile rows used in the design—guidelines are provided in the "Spine Architecture" section of the *IGLOO FPGA Fabric User Guide*.

$F_{CLK}$  is the global clock signal frequency.

$N_{S-CELL}$  is the number of VersaTiles used as sequential modules in the design.

$P_{AC1}$ ,  $P_{AC2}$ ,  $P_{AC3}$ , and  $P_{AC4}$  are device-dependent.

#### **Sequential Cells Contribution— $P_{S-CELL}$**

$$P_{S-CELL} = N_{S-CELL} * (P_{AC5} + \alpha_1 / 2 * P_{AC6}) * F_{CLK}$$

$N_{S-CELL}$  is the number of VersaTiles used as sequential modules in the design. When a multi-tile sequential cell is used, it should be accounted for as 1.

$\alpha_1$  is the toggle rate of VersaTile outputs—guidelines are provided in Table 2-23 on page 2-19.

$F_{CLK}$  is the global clock signal frequency.

**Table 2-36 • Summary of I/O Timing Characteristics—Software Default Settings, Std. Speed Grade, Commercial-Case Conditions:  $T_J = 70^\circ\text{C}$ , Worst-Case  $V_{CC} = 1.14 \text{ V}$ , Worst-Case VCCI (per standard)**  
**Applicable to Standard I/O Banks**

I/O Standard	Drive Strength	Equivalent Software Default Drive Strength Option <sup>1</sup> (mA)	Slew Rate	Capacitive Load (pF)	External Resistor ( $\Omega$ )	$t_{DOUT}$ (ns)	$t_{DIN}$ (ns)	$t_{PY}$ (ns)	$t_{EOUT}$ (ns)	$t_{ZL}$ (ns)	$t_{ZH}$ (ns)	$t_{LZ}$ (ns)	$t_{HZ}$ (ns)	Units	
3.3 V LVTTL / 3.3 V LVCMOS	8 mA	8	High	5	–	1.55	2.38	0.26	0.94	1.10	2.41	1.92	2.40	2.96	ns
3.3 V LVCMOS Wide Range <sup>3</sup>	100 $\mu\text{A}$	8	High	5	–	1.55	3.33	0.26	1.29	1.10	3.33	2.62	3.34	4.07	ns
2.5 V LVCMOS	8 mA	8	High	5	–	1.55	2.39	0.26	1.15	1.10	2.42	2.05	2.38	2.80	ns
1.8 V LVCMOS	4 mA	4	High	5	–	1.55	2.60	0.26	1.08	1.10	2.64	2.33	2.38	2.62	ns
1.5 V LVCMOS	2 mA	2	High	5	–	1.55	2.92	0.26	1.22	1.10	2.96	2.60	2.40	2.56	ns
1.2 V LVCMOS	1 mA	1	High	5	–	1.55	3.59	0.26	1.53	1.10	3.47	3.06	2.51	2.49	ns
1.2 V LVCMOS Wide Range <sup>3</sup>	100 $\mu\text{A}$	1	High	5	–	1.55	3.59	0.26	1.53	1.10	3.47	3.06	2.51	2.49	ns

Notes:

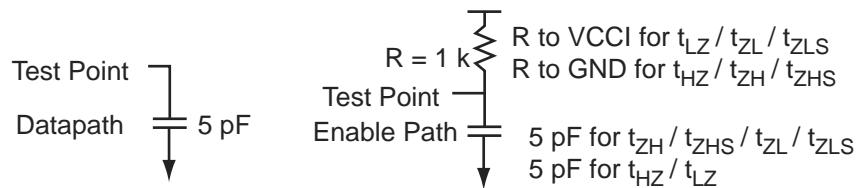
1. The minimum drive strength for any LVCMOS 1.2 V or LVCMOS 3.3 V software configuration when run in wide range is  $\pm 100 \mu\text{A}$ . Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.
2. All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD-8B specification.
3. All LVCMOS 1.2 V software macros support LVCMOS 1.2 V wide range as specified in the JESD8-12 specification
4. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-7 for derating values.

**Table 2-81 • Minimum and Maximum DC Input and Output Levels Applicable to Standard I/O Banks**

2.5 V LVC MOS	VIL		VIH		VOL	VOH	IOL	IOH	IOSH	IOSL	IIL <sup>1</sup>	IIH <sup>2</sup>
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA <sup>3</sup>	Max. mA <sup>3</sup>	µA <sup>4</sup>	µA <sup>4</sup>
2 mA	-0.3	0.7	1.7	3.6	0.7	1.7	2	2	16	18	10	10
4 mA	-0.3	0.7	1.7	3.6	0.7	1.7	4	4	16	18	10	10
6 mA	-0.3	0.7	1.7	3.6	0.7	1.7	6	6	32	37	10	10
8 mA	-0.3	0.7	1.7	3.6	0.7	1.7	8	8	32	37	10	10

Notes:

1. *IIL* is the input leakage current per I/O pin over recommended operation conditions where  $-0.3 \text{ V} < \text{VIN} < \text{VIL}$ .
2. *IIH* is the input leakage current per I/O pin over recommended operating conditions  $\text{VIH} < \text{VIN} < \text{VCCI}$ . Input current is larger when operating outside recommended ranges
3. Currents are measured at 100°C junction temperature and maximum voltage.
4. Currents are measured at 85°C junction temperature.
5. Software default selection highlighted in gray.



**Figure 2-8 • AC Loading**

**Table 2-82 • AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	C <sub>LOAD</sub> (pF)
0	2.5	1.2	5

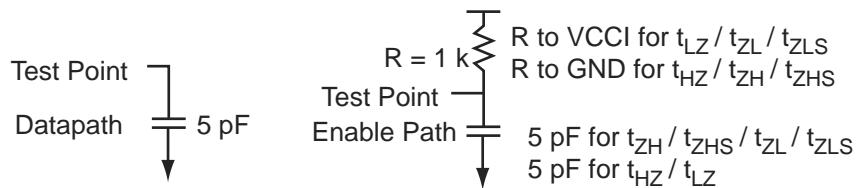
Note: \*Measuring point =  $\text{Vtrip}$ . See Table 2-29 on page 2-28 for a complete table of trip points.

**Table 2-113 • Minimum and Maximum DC Input and Output Levels Applicable to Standard I/O Banks**

1.5 V LVC MOS	VIL		VIH		VOL	VOH	IOL	IOH	IOSH	IOSL	IIL <sup>1</sup>	IIH <sup>2</sup>
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA <sup>3</sup>	Max. mA <sup>3</sup>	µA <sup>4</sup>	µA <sup>4</sup>
2 mA	-0.3	0.35 * VCCI	0.65 * VCCI	3.6	0.25 * VCCI	0.75 * VCCI	2	2	13	16	10	10

Notes:

1. *IIL* is the input leakage current per I/O pin over recommended operation conditions where  $-0.3 \text{ V} < \text{VIN} < \text{VIL}$ .
2. *IIH* is the input leakage current per I/O pin over recommended operating conditions  $\text{VIH} < \text{VIN} < \text{VCCI}$ . Input current is larger when operating outside recommended ranges.
3. Currents are measured at  $100^\circ\text{C}$  junction temperature and maximum voltage.
4. Currents are measured at  $85^\circ\text{C}$  junction temperature.
5. Software default selection highlighted in gray.



**Figure 2-10 • AC Loading**

**Table 2-114 • AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	C <sub>LOAD</sub> (pF)
0	1.5	0.75	5

Note: \*Measuring point = Vtrip. See Table 2-29 on page 2-28 for a complete table of trip points.

## 1.2 V LVCMOS (JESD8-12A)

Low-Voltage CMOS for 1.2 V complies with the LVCMOS standard JESD8-12A for general purpose 1.2 V applications. It uses a 1.2 V input buffer and a push-pull output buffer. Furthermore, all LVCMOS 1.2 V software macros comply with LVCMOS 1.2 V wide range as specified in the JESD8-12A specification.

**Table 2-127 • Minimum and Maximum DC Input and Output Levels Applicable to Advanced I/O Banks**

1.2 V LVCMOS	VIL		VIH		VOL	VOH	IOL	IOH	IOSH	IOSL	IIL <sup>1</sup>	IIH <sup>2</sup>
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA <sup>3</sup>	Max. mA <sup>3</sup>	µA <sup>4</sup>	µA <sup>4</sup>
2 mA	-0.3	0.35 * VCCI	0.65 * VCCI	1.26	0.25 * VCCI	0.75 * VCCI	2	2	20	26	10	10

Notes:

1. *IIL* is the input leakage current per I/O pin over recommended operation conditions where  $-0.3 \text{ V} < \text{VIN} < \text{VIL}$ .
2. *IIH* is the input leakage current per I/O pin over recommended operating conditions  $\text{VIH} < \text{VIN} < \text{VCCI}$ . Input current is larger when operating outside recommended ranges
3. Currents are measured at 100°C junction temperature and maximum voltage.
4. Currents are measured at 85°C junction temperature.
5. Software default selection highlighted in gray.

**Table 2-128 • Minimum and Maximum DC Input and Output Levels Applicable to Standard Plus I/O Banks**

1.2 V LVCMOS	VIL		VIH		VOL	VOH	I <sub>OL</sub>	IOH	IOSH	IOSL	IIL <sup>1</sup>	IIH <sup>2</sup>
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA <sup>3</sup>	Max. mA <sup>3</sup>	µA <sup>4</sup>	µA <sup>4</sup>
2 mA	-0.3	0.35 * VCCI	0.65 * VCCI	1.26	0.25 * VCCI	0.75 * VCCI	2	2	20	26	10	10

Notes:

1. *IIL* is the input leakage current per I/O pin over recommended operation conditions where  $-0.3 \text{ V} < \text{VIN} < \text{VIL}$ .
2. *IIH* is the input leakage current per I/O pin over recommended operating conditions  $\text{VIH} < \text{VIN} < \text{VCCI}$ . Input current is larger when operating outside recommended ranges
3. Currents are measured at 100°C junction temperature and maximum voltage.
4. Currents are measured at 85°C junction temperature.
5. Software default selection highlighted in gray.

**Table 2-129 • Minimum and Maximum DC Input and Output Levels Applicable to Standard I/O Banks**

1.2 V LVCMOS	VIL		VIH		VOL	VOH	IOL	IOH	IOSH	IOSL	IIL <sup>1</sup>	IIH <sup>2</sup>
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA <sup>3</sup>	Max. mA <sup>3</sup>	µA <sup>4</sup>	µA <sup>4</sup>
1 mA	-0.3	0.35 * VCCI	0.65 * VCCI	3.6	0.25 * VCCI	0.75 * VCCI	1	1	20	26	10	10

Notes:

1. *IIL* is the input leakage current per I/O pin over recommended operation conditions where  $-0.3 \text{ V} < \text{VIN} < \text{VIL}$ .
2. *IIH* is the input leakage current per I/O pin over recommended operating conditions  $\text{VIH} < \text{VIN} < \text{VCCI}$ . Input current is larger when operating outside recommended ranges
3. Currents are measured at 100°C junction temperature and maximum voltage.
4. Currents are measured at 85°C junction temperature.
5. Software default selection highlighted in gray.

## DDR Module Specifications

### *Input DDR Module*

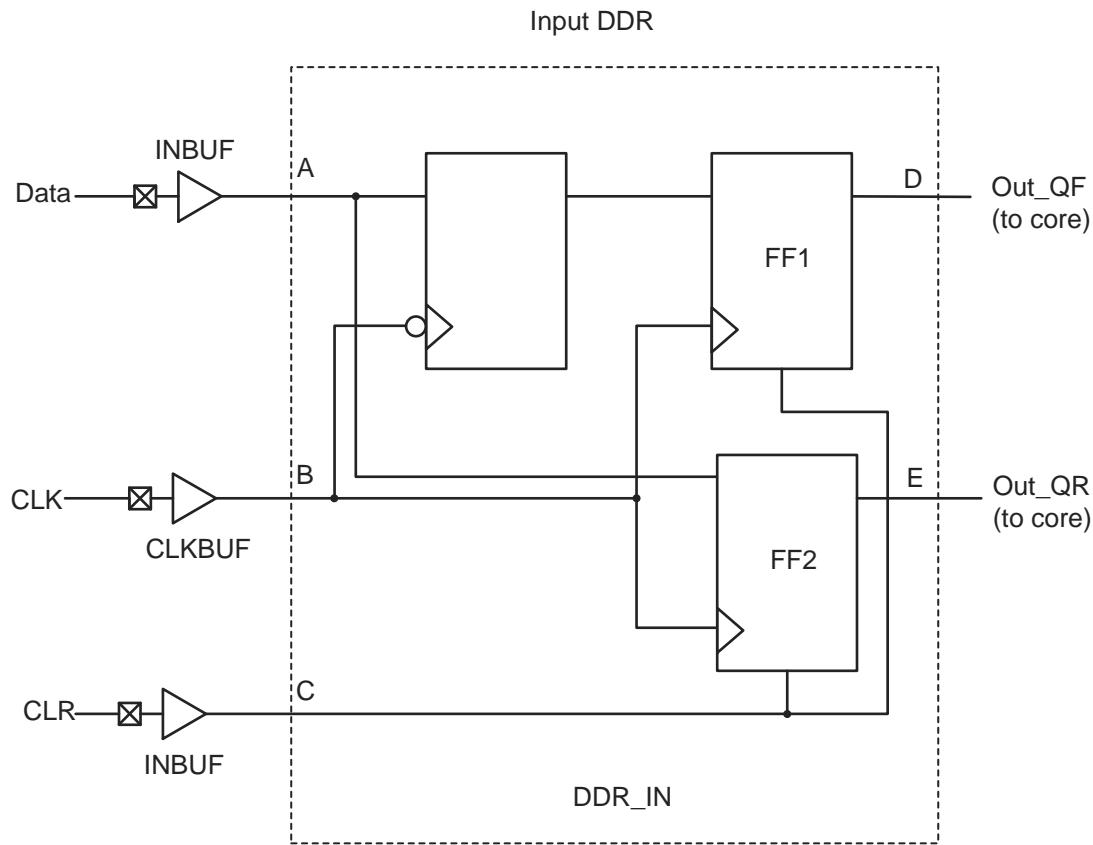


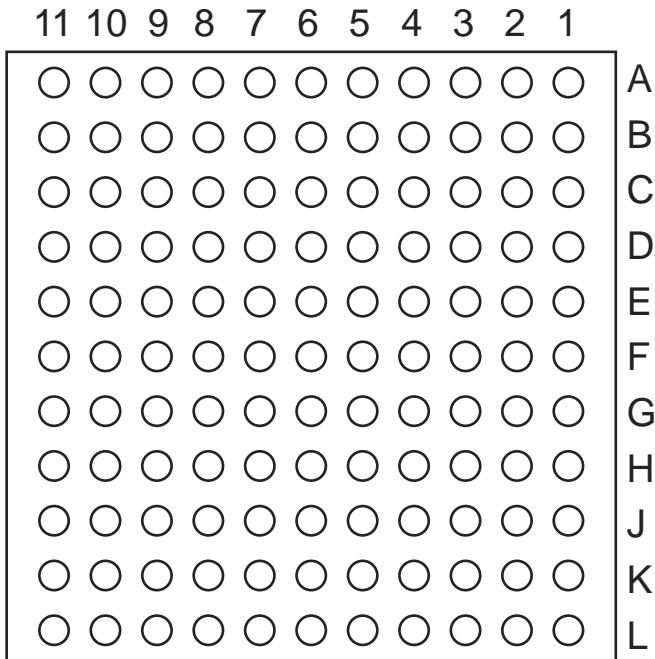
Figure 2-21 • Input DDR Timing Model

Table 2-163 • Parameter Definitions

Parameter Name	Parameter Definition	Measuring Nodes (from, to)
$t_{DDRICLKQ1}$	Clock-to-Out Out_QR	B, D
$t_{DDRICLKQ2}$	Clock-to-Out Out_QF	B, E
$t_{DDRISUD}$	Data Setup Time of DDR input	A, B
$t_{DDRIHD}$	Data Hold Time of DDR input	A, B
$t_{DDRICLR2Q1}$	Clear-to-Out Out_QR	C, D
$t_{DDRICLR2Q2}$	Clear-to-Out Out_QF	C, E
$t_{DDRIREMCLR}$	Clear Removal	C, B
$t_{DDRIRECCLR}$	Clear Recovery	C, B

## CS121

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*Note: This is the bottom view of the package.*

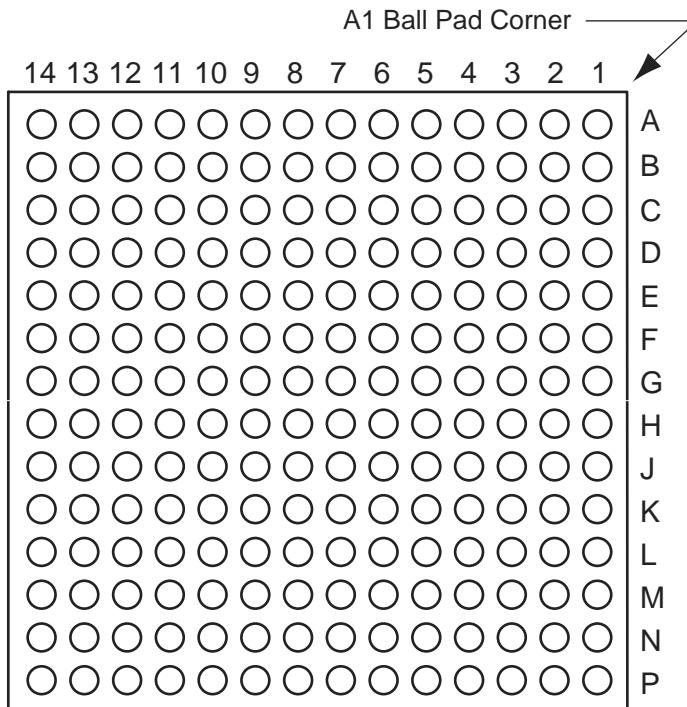
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### Note

For more information on package drawings, see PD3068: Package Mechanical Drawings.

## CS196

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*Note: This is the bottom view of the package.*

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### **Note**

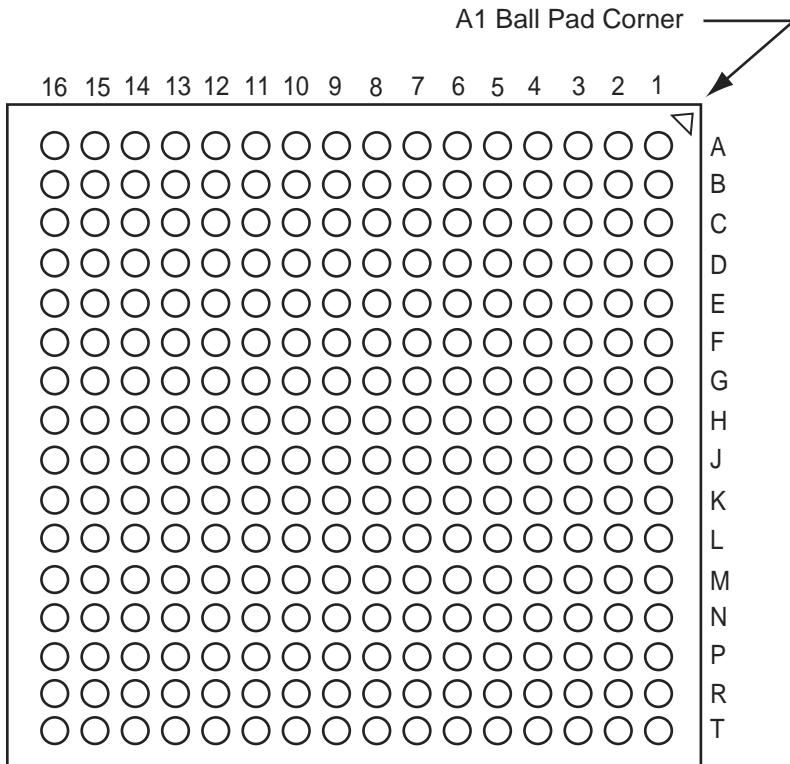
For more information on package drawings, see *PD3068: Package Mechanical Drawings*.

<b>QN68</b>	
<b>Pin Number</b>	<b>AGL015 Function</b>
1	IO82RSB1
2	IO80RSB1
3	IO78RSB1
4	IO76RSB1
5	GEC0/IO73RSB1
6	GEA0/IO72RSB1
7	GEB0/IO71RSB1
8	VCC
9	GND
10	VCCIB1
11	IO68RSB1
12	IO67RSB1
13	IO66RSB1
14	IO65RSB1
15	IO64RSB1
16	IO63RSB1
17	IO62RSB1
18	FF/IO60RSB1
19	IO58RSB1
20	IO56RSB1
21	IO54RSB1
22	IO52RSB1
23	IO51RSB1
24	VCC
25	GND
26	VCCIB1
27	IO50RSB1
28	IO48RSB1
29	IO46RSB1
30	IO44RSB1
31	IO42RSB1
32	TCK
33	TDI
34	TMS
35	VPUMP
36	TDO

<b>QN68</b>	
<b>Pin Number</b>	<b>AGL015 Function</b>
37	TRST
38	VJTAG
39	IO40RSB0
40	IO37RSB0
41	GDB0/IO34RSB0
42	GDA0/IO33RSB0
43	GDC0/IO32RSB0
44	VCCIB0
45	GND
46	VCC
47	IO31RSB0
48	IO29RSB0
49	IO28RSB0
50	IO27RSB0
51	IO25RSB0
52	IO24RSB0
53	IO22RSB0
54	IO21RSB0
55	IO19RSB0
56	IO17RSB0
57	IO15RSB0
58	IO14RSB0
59	VCCIB0
60	GND
61	VCC
62	IO12RSB0
63	IO10RSB0
64	IO08RSB0
65	IO06RSB0
66	IO04RSB0
67	IO02RSB0
68	IO00RSB0

## FG256

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*Note: This is the bottom view of the package.*

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### Note

For more information on package drawings, see *PD3068: Package Mechanical Drawings*.

<b>FG256</b>	
<b>Pin Number</b>	<b>AGL1000 Function</b>
H3	GFB1/IO208PPB3
H4	VCOMPLF
H5	GFC0/IO209NPB3
H6	VCC
H7	GND
H8	GND
H9	GND
H10	GND
H11	VCC
H12	GCC0/IO91NPB1
H13	GCB1/IO92PPB1
H14	GCA0/IO93NPB1
H15	IO96NPB1
H16	GCB0/IO92NPB1
J1	GFA2/IO206PSB3
J2	GFA1/IO207PDB3
J3	VCCPLF
J4	IO205NDB3
J5	GFB2/IO205PDB3
J6	VCC
J7	GND
J8	GND
J9	GND
J10	GND
J11	VCC
J12	GCB2/IO95PPB1
J13	GCA1/IO93PPB1
J14	GCC2/IO96PPB1
J15	IO100PPB1
J16	GCA2/IO94PSB1
K1	GFC2/IO204PDB3
K2	IO204NDB3
K3	IO203NDB3
K4	IO203PDB3
K5	VCCIB3
K6	VCC
K7	GND
K8	GND

<b>FG256</b>	
<b>Pin Number</b>	<b>AGL1000 Function</b>
K9	GND
K10	GND
K11	VCC
K12	VCCIB1
K13	IO95NPB1
K14	IO100NPB1
K15	IO102NDB1
K16	IO102PDB1
L1	IO202NDB3
L2	IO202PDB3
L3	IO196PPB3
L4	IO193PPB3
L5	VCCIB3
L6	GND
L7	VCC
L8	VCC
L9	VCC
L10	VCC
L11	GND
L12	VCCIB1
L13	GDB0/IO112NPB1
L14	IO106NDB1
L15	IO106PDB1
L16	IO107PDB1
M1	IO197NSB3
M2	IO196NPB3
M3	IO193NPB3
M4	GEC0/IO190NPB3
M5	VMV3
M6	VCCIB2
M7	VCCIB2
M8	IO147RSB2
M9	IO136RSB2
M10	VCCIB2
M11	VCCIB2
M12	VMV2
M13	IO110NDB1
M14	GDB1/IO112PPB1

<b>FG256</b>	
<b>Pin Number</b>	<b>AGL1000 Function</b>
M15	GDC1/IO111PDB1
M16	IO107NDB1
N1	IO194PSB3
N2	IO192PPB3
N3	GEC1/IO190PPB3
N4	IO192NPB3
N5	GNDQ
N6	GEA2/IO187RSB2
N7	IO161RSB2
N8	IO155RSB2
N9	IO141RSB2
N10	IO129RSB2
N11	IO124RSB2
N12	GNDQ
N13	IO110PDB1
N14	VJTAG
N15	GDC0/IO111NDB1
N16	GDA1/IO113PDB1
P1	GEB1/IO189PDB3
P2	GEB0/IO189NDB3
P3	VMV2
P4	IO179RSB2
P5	IO171RSB2
P6	IO165RSB2
P7	IO159RSB2
P8	IO151RSB2
P9	IO137RSB2
P10	IO134RSB2
P11	IO128RSB2
P12	VMV1
P13	TCK
P14	VPUMP
P15	TRST
P16	GDA0/IO113NDB1
R1	GEA1/IO188PDB3
R2	GEA0/IO188NDB3
R3	IO184RSB2
R4	GEC2/IO185RSB2

<b>FG484</b>	
<b>Pin Number</b>	<b>AGL400 Function</b>
B7	NC
B8	NC
B9	NC
B10	NC
B11	NC
B12	NC
B13	NC
B14	NC
B15	NC
B16	NC
B17	NC
B18	NC
B19	NC
B20	NC
B21	VCCIB1
B22	GND
C1	VCCIB3
C2	NC
C3	NC
C4	NC
C5	GND
C6	NC
C7	NC
C8	VCC
C9	VCC
C10	NC
C11	NC
C12	NC
C13	NC
C14	VCC
C15	VCC
C16	NC
C17	NC
C18	GND
C19	NC
C20	NC

<b>FG484</b>	
<b>Pin Number</b>	<b>AGL400 Function</b>
R9	VCCIB2
R10	VCCIB2
R11	IO108RSB2
R12	IO101RSB2
R13	VCCIB2
R14	VCCIB2
R15	VMV2
R16	IO83RSB2
R17	GDB1/IO78UPB1
R18	GDC1/IO77UDB1
R19	IO75NDB1
R20	VCC
R21	NC
R22	NC
T1	NC
T2	NC
T3	NC
T4	IO140NDB3
T5	IO138PPB3
T6	GEC1/IO137PPB3
T7	IO131RSB2
T8	GNDQ
T9	GEA2/IO134RSB2
T10	IO117RSB2
T11	IO111RSB2
T12	IO99RSB2
T13	IO94RSB2
T14	IO87RSB2
T15	GNDQ
T16	IO93RSB2
T17	VJTAG
T18	GDC0/IO77VDB1
T19	GDA1/IO79UDB1
T20	NC
T21	NC
T22	NC

<b>FG484</b>	
<b>Pin Number</b>	<b>AGL400 Function</b>
U1	NC
U2	NC
U3	NC
U4	GEB1/IO136PDB3
U5	GEB0/IO136NDB3
U6	VMV2
U7	IO129RSB2
U8	IO128RSB2
U9	IO122RSB2
U10	IO115RSB2
U11	IO110RSB2
U12	IO98RSB2
U13	IO95RSB2
U14	IO88RSB2
U15	IO84RSB2
U16	TCK
U17	VPUMP
U18	TRST
U19	GDA0/IO79VDB1
U20	NC
U21	NC
U22	NC
V1	NC
V2	NC
V3	GND
V4	GEA1/IO135PDB3
V5	GEA0/IO135NDB3
V6	IO127RSB2
V7	GEC2/IO132RSB2
V8	IO123RSB2
V9	IO118RSB2
V10	IO112RSB2
V11	IO106RSB2
V12	IO100RSB2
V13	IO96RSB2
V14	IO89RSB2

<b>FG484</b>	
<b>Pin Number</b>	<b>AGL400 Function</b>
Y7	NC
Y8	VCC
Y9	VCC
Y10	NC
Y11	NC
Y12	NC
Y13	NC
Y14	VCC
Y15	VCC
Y16	NC
Y17	NC
Y18	GND
Y19	NC
Y20	NC
Y21	NC
Y22	VCCIB1

*Package Pin Assignments*

<b>FG484</b>	
<b>Pin Number</b>	<b>AGL600 Function</b>
R9	VCCIB2
R10	VCCIB2
R11	IO117RSB2
R12	IO110RSB2
R13	VCCIB2
R14	VCCIB2
R15	VMV2
R16	IO94RSB2
R17	GDB1/IO87PPB1
R18	GDC1/IO86PDB1
R19	IO84NDB1
R20	VCC
R21	IO81NDB1
R22	IO82PDB1
T1	IO152PDB3
T2	IO152NDB3
T3	NC
T4	IO150NDB3
T5	IO147PPB3
T6	GEC1/IO146PPB3
T7	IO140RSB2
T8	GNDQ
T9	GEA2/IO143RSB2
T10	IO126RSB2
T11	IO120RSB2
T12	IO108RSB2
T13	IO103RSB2
T14	IO99RSB2
T15	GNDQ
T16	IO92RSB2
T17	VJTAG
T18	GDC0/IO86NDB1
T19	GDA1/IO88PDB1
T20	NC
T21	IO83PDB1
T22	IO82NDB1

<b>FG484</b>	
<b>Pin Number</b>	<b>AGL1000 Function</b>
N17	IO100NPB1
N18	IO102NDB1
N19	IO102PDB1
N20	NC
N21	IO101NPB1
N22	IO103PDB1
P1	NC
P2	IO199PDB3
P3	IO199NDB3
P4	IO202NDB3
P5	IO202PDB3
P6	IO196PPB3
P7	IO193PPB3
P8	VCCIB3
P9	GND
P10	VCC
P11	VCC
P12	VCC
P13	VCC
P14	GND
P15	VCCIB1
P16	GDB0/IO112NPB1
P17	IO106NDB1
P18	IO106PDB1
P19	IO107PDB1
P20	NC
P21	IO104PDB1
P22	IO103NDB1
R1	NC
R2	IO197PPB3
R3	VCC
R4	IO197NPB3
R5	IO196NPB3
R6	IO193NPB3
R7	GEC0/IO190NPB3
R8	VMV3

<b>FG484</b>	
<b>Pin Number</b>	<b>AGL1000 Function</b>
U1	IO195PDB3
U2	IO195NDB3
U3	IO194NPB3
U4	GEB1/IO189PDB3
U5	GEB0/IO189NDB3
U6	VMV2
U7	IO179RSB2
U8	IO171RSB2
U9	IO165RSB2
U10	IO159RSB2
U11	IO151RSB2
U12	IO137RSB2
U13	IO134RSB2
U14	IO128RSB2
U15	VMV1
U16	TCK
U17	VPUMP
U18	TRST
U19	GDA0/IO113NDB1
U20	NC
U21	IO108NDB1
U22	IO109PDB1
V1	NC
V2	NC
V3	GND
V4	GEA1/IO188PDB3
V5	GEA0/IO188NDB3
V6	IO184RSB2
V7	GEC2/IO185RSB2
V8	IO168RSB2
V9	IO163RSB2
V10	IO157RSB2
V11	IO149RSB2
V12	IO143RSB2
V13	IO138RSB2
V14	IO131RSB2